

Abstract of the Disclosure

By means of a pump for supplying a processing fluid such as a plating fluid to a closed processing cup such as a closed plating cup, at least either the pressure or flow rate of the processing fluid or plating fluid circulating within the closed processing cup or the closed plating cup is cyclically changed. Further, the direction of circulation of the processing fluid circulating within the closed processing cup is also changed cyclically. Under a method of manufacturing a semiconductor device and a method of manufacturing a printed board, a semiconductor wafer and a printed board are disposed in the closed plating cup such that blind holes formed by closing openings on one end of via holes or openings on one end of through holes are brought into contact with a circulating plating fluid, thereby eliminating air bubbles that remain. As a result, a manufacturing yield or performance of a product is improved.